

## Package of light emitting diode chip and its condensing lens

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### Abstract of TW 479378 (B)

A package for light emitting diode (LED) chip is disclosed in the present invention and includes the followings: a printed circuit board (PCB), which is provided with a conductor layer and an electrode such that both conductor layer and electrode are located on one face of the PCB; a light emitting diode chip, which is disposed on the conductor layer and is provided with a conducting wire for connecting with the electrode; and a condensing lens with a roughly short pillar shape, in which the condensing lens corresponds to the position of LED chip and is bonded to the PCB. In addition, both opposite terminals of the condensing lens are provided with a concave curved-surface and a convex curved-surface, respectively. The concave curved-surface is close to and faces the LED chip; while the convex curved-surface is far from the LED chip and is approximately in parallel with the concave curved-surface. Additionally, a distance is remained between the concave curved-surface and the LED chip.

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